

Specification of Thermoelectric Module

TEHC1-03108

Description

The 31 couples, 20 mm × 20 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 74° C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- High effective cooling and efficiency
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly ,RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

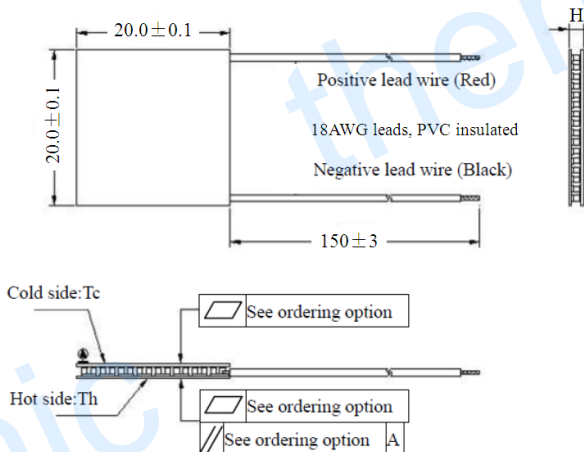
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N2
DTmax (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
Umax (Voltage)	4.1	4.4	Voltage applied to the module at DTmax
Imax (Amps)	8.5	8.5	DC current through the modules at DTmax
QCmax (Watts)	21.7	23.3	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (Ohms)	0.36	0.39	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Ordering Option

Suffix	Thickness H / (mm)	Flatness/ Parallellism (mm)	Lead wire length (mm) Standard/Optional length
TF	0:3.5±0.10	0:0.05/0.05	150±3/Specify
TF	1:3.5±0.05	1:0.025/0.025	150±3/Specify
TF	2:3.5±0.025	2:0.015/0.015	150±3/Specify

Eg. TF01: Thickness 3.5±0.10(mm) and Flatness 0.025/0.025(mm)

Manufacturing Options

A. Solder:

1. T100: BiSn (Melting Point=138°C)
2. T200: CuSn (Melting Point= 227 °C)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant
4. Customer specify sealing

C. Ceramics:

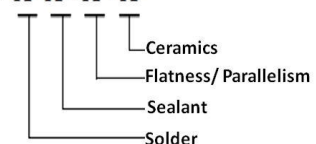
1. Alumina (Al₂O₃, white 96%)(AIO)
2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized (Copper-Nickel plating)

Naming for the Module

TEHC1-03108- X -X - X - X



TEHC1-03108-T100-NS -TF01 -AIO

T100: BiSn (Tmelt=138°C)

NS: No sealing

AIO: Alumina (Al₂O₃, white 96%)

TF01: Thickness ± 0.1(mm) and Flatness/ Parallellism: 0.025/0.025 (mm)

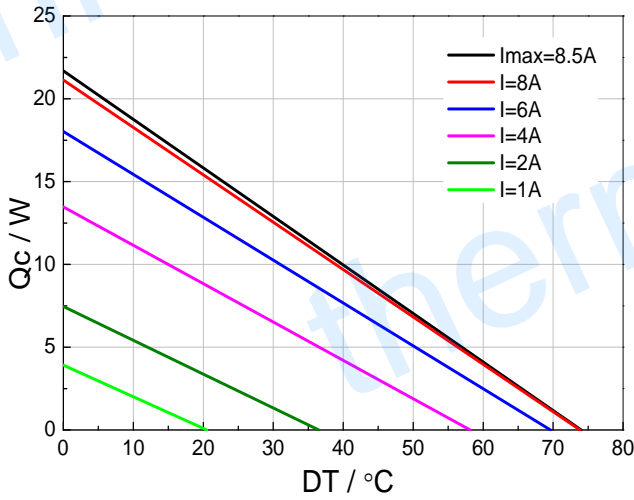
Creative technology with fine manufacturing processes provides you the reliable and quality products

Tel: +86-791-88198288 Fax: +86-791-88198308 Email: sales@thermonamic.com.cn Web Site: www.thermonamic.com.cn

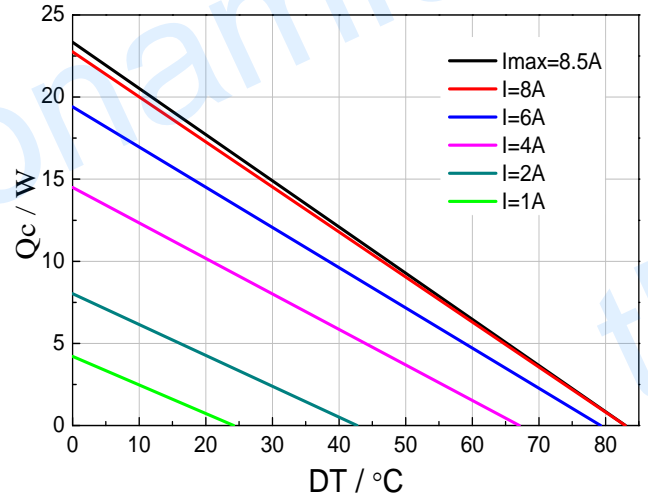
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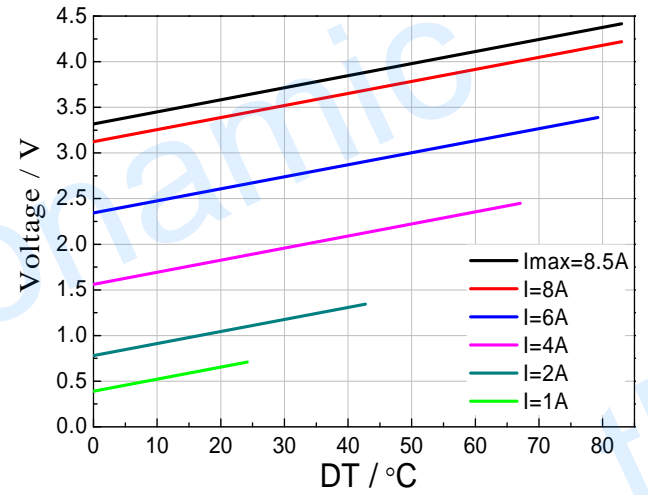
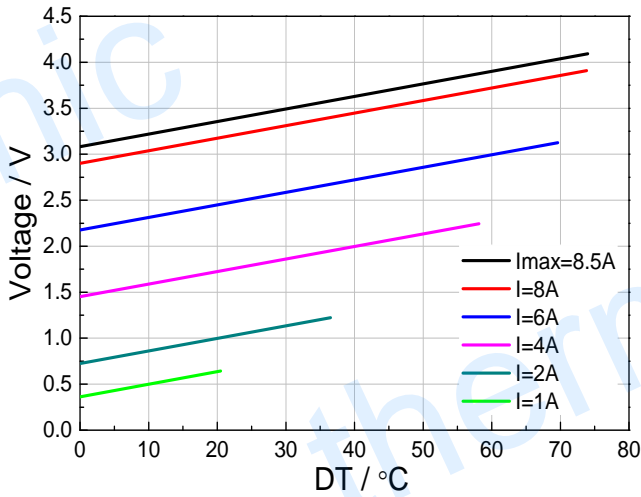
Performance Curves at $T_h=27\text{ }^\circ\text{C}$



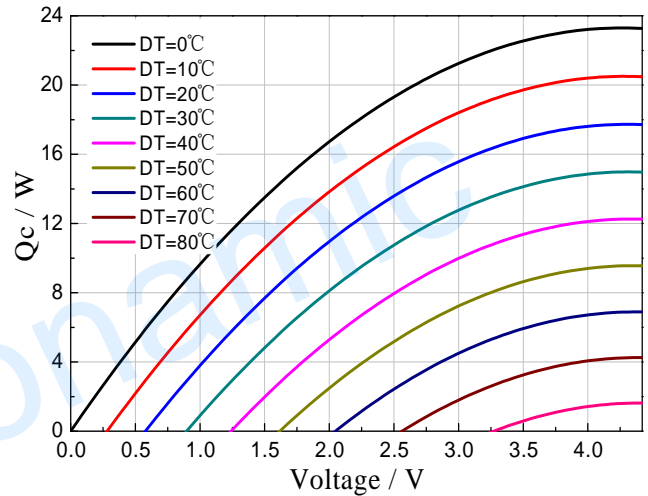
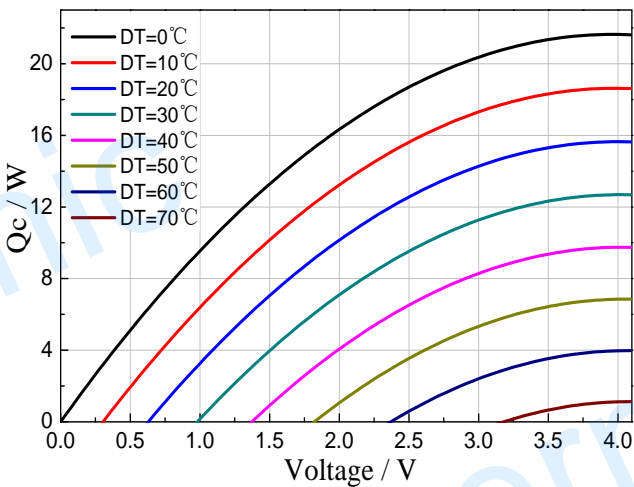
Performance Curves at $T_h=50\text{ }^\circ\text{C}$



Standard Performance Graph $Q_c = f(DT)$



Standard Performance Graph $V = f(DT)$



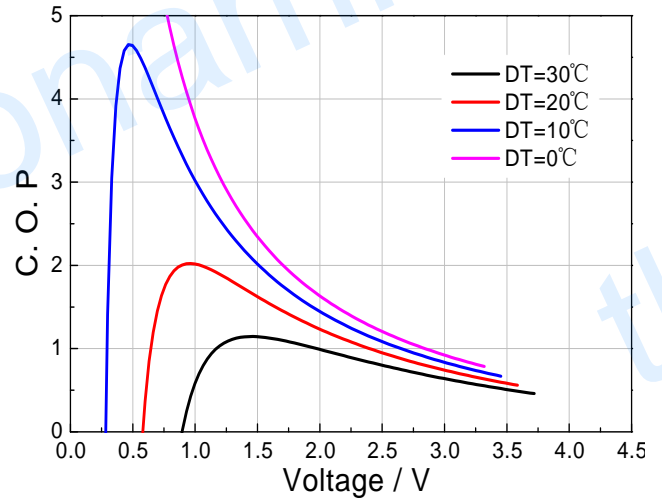
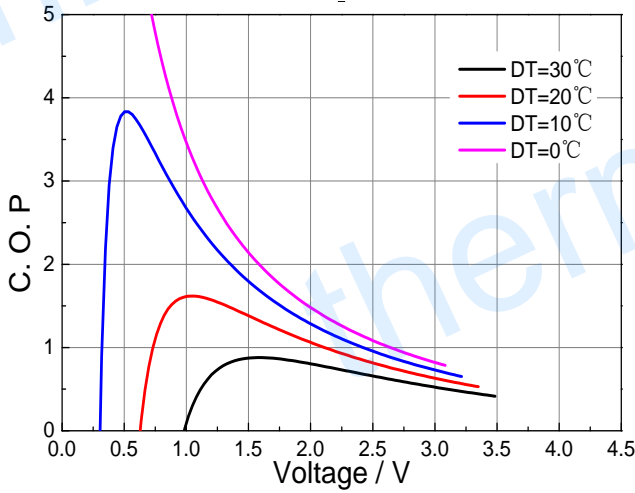
Standard Performance Graph $Q_c = f(V)$

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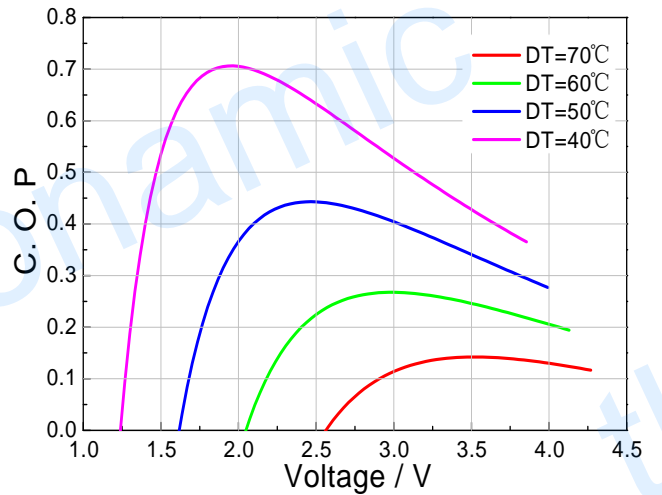
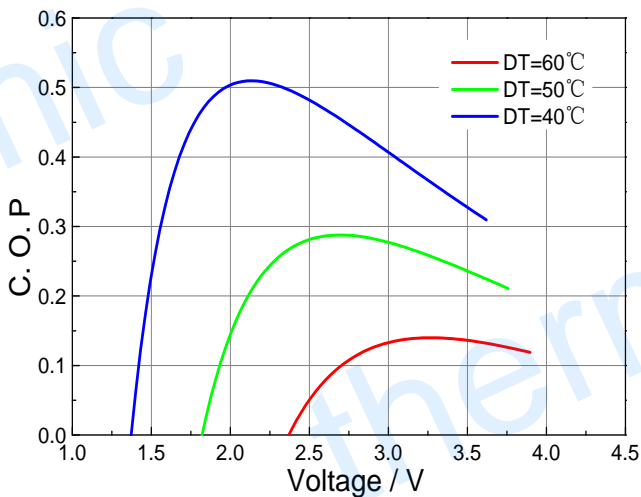
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Performance Curves at Th=27 °C

Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

Operation Cautions

- Cold side of the module stucked on the object being cooled
- Hot side of the module mounted on a heat radiator
- Operation or storage module below melting point of solder
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.